voltage or as a board for LED mounting having a large amount of heat generation, while maintaining insulating properties between circuit wirings and insulating properties between each circuit wiring and a support metal layer. Moreover, in the case where a copper foil for forming a circuit is sequentially laminated in a customer's process like in the tape automated bonding method, the adhesive layer is sandwiched between the copper foil for forming a circuit and the support copper foil and there is no refuge of the water absorbed by the adhesive layer, and therefore, there is a problem that foaming is produced in the adhesive layer.

PRIOR ART DOCUMENTS

PATENT DOCUMENTS

[0008]

Patent Document 1: Japanese Unexamined Patent Publication No. 8-288605

Patent Document 2: Japanese Unexamined Patent Publication No. 8-055880

SUMMARY OF THE INVENTION

PROBLEMS TO BE SOLVED BY THE INVENTION

[0009]

Embodiments ~~It is an object~~ of the present invention ~~to~~ provide a metal support flexible board which has excellent wire bonding

properties and low curling properties while maintaining excellent insulating properties and punching properties, and therefore can be subjected to a reel-to-reel process and facilitates packaging scheme and heat dissipation scheme.

MEANS FOR SOLVING THE PROBLEMS

[0010]

~~In order to solve the above-mentioned problems, in a metal support flexible board of the present invention, a support is composed of a metal foil, and (1) an adhesive layer contains (A) a polyamide resin containing a dimer acid residue and (B) a phenol resin.~~

According to a first aspect, there is provided a metal support flexible board comprising an adhesive layer and a support, wherein a support-covering layer is formed on the adhesive layer side of the support and the opposite side thereof, and the support is composed of a metal foil, and the adhesive layer contains a polyamide resin containing a dimer acid residue and a phenol resin.

[0010a]

According to a second aspect, there is provided a metal support carrier tape for tape automated bonding using the above metal support flexible board.

[0010b]

According to a third aspect, there is provided a metal support flexible circuit board for mounting an LED using the above metal support flexible board.

[0010c]

According to a fourth aspect, there is provided a copper foil-laminated metal support flexible circuit board for forming a circuit using the above metal support flexible board, wherein a circuit formed by a metal layer for forming a circuit has a flying lead structure.

EFFECTS OF THE INVENTION

[0011]

In accordance with embodiments of the present invention, since a metal support flexible board has excellent wire bonding properties and low curling properties while maintaining excellent insulating properties and punching properties, it becomes possible to facilitate packaging scheme and heat dissipation scheme. Electronic parts using the metal support flexible board of the present invention have chemical resistance necessary for circuit processing and insulating properties which enable high-voltage driving in a circuit of a metal support board, can be easily subjected to a reel-to-reel process and a punching